### MICROWAVE POWER GaAs FET

# Internally Matched Power GaAs FETs (C-Band)

#### **Features**

- · High power
  - $P_{1dB}$  = 42.5 dBm at 5.0 GHz to 5.3 GHz
- · High gain
- G<sub>1dB</sub> = 8 dB at 5.0 GHz to 5.3 GHz
   Broad band internally matched
- · Hermetically sealed package

# RF Performance Specifications ( $T_a = 25^{\circ} C$ )

Characteristics	Symbol	Condition	Unit	Min.	Тур.	Max
Output Power at 1dB Compression Point	P <sub>1dB</sub>		dBm	41.5	42.5	_
Power Gain at 1dB Compression Point	G <sub>1dB</sub>	$V_{DS} = 10V$ f = 5.0 ~ 5.3 GHz	dB	7.0	8.0	_
Drain Current	I <sub>DS</sub>		А	_	4.8	5.5
Power Added Efficiency	η <sub>add</sub>		%	_	31	_
Channel-Temperature Rise	ΔT <sub>ch</sub>	V <sub>DS</sub> xI <sub>DS</sub> xR <sub>th</sub> (c-c)	°C	_	_	80

## Electrical Characteristics (T<sub>a</sub> = 25° C)

Characteristic	Symbol	Condition	Unit	Min.	Тур.	Max
Trans-conductance	gm	$V_{DS} = 3V$ $I_{DS} = 6.0 \text{ A}$	mS	_	3600	_
Pinch-off Voltage	V <sub>GSoff</sub>	$V_{DS} = 3V$ $I_{DS} = 80 \text{mA}$	V	-2.0	-3.5	-5.0
Saturated Drain Current	I <sub>DSS</sub>	$V_{DS} = 3V$ $V_{GS} = 0V$	А	_	11.6	15.0
Gate to Source Breakdown Voltage	$V_{GSO}$	I <sub>GS</sub> = -240 μA	V	-5	_	-
Thermal Resistance	R <sub>th (c-c)</sub>	Channel to case	°C/W	_	1.4	1.8

The information contained here is subject to change without notice.

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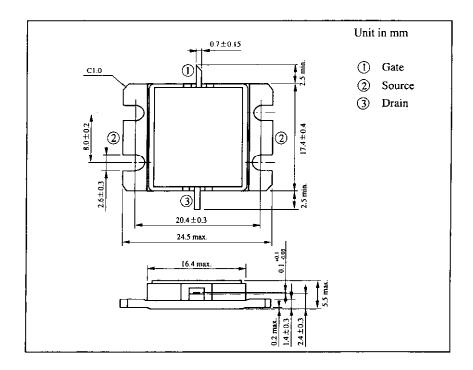
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# Absolute Maximum Ratings ( $T_a = 25^{\circ} C$ )

Characteristic	Symbol	Unit	Rating
Drain Source Voltage	V <sub>DS</sub>	V	15
Gate Source Voltage	V <sub>GS</sub>	V	-5
Drain Current	I <sub>D</sub>	А	16
Total Power Dissipation (Tc = 25°C)	P <sub>T</sub>	W	70
Channel Temperature	T <sub>ch</sub>	°C	175
Storage Temperature	T <sub>stg</sub>	°C	-65~175

### Package Outline (2-16G1B)



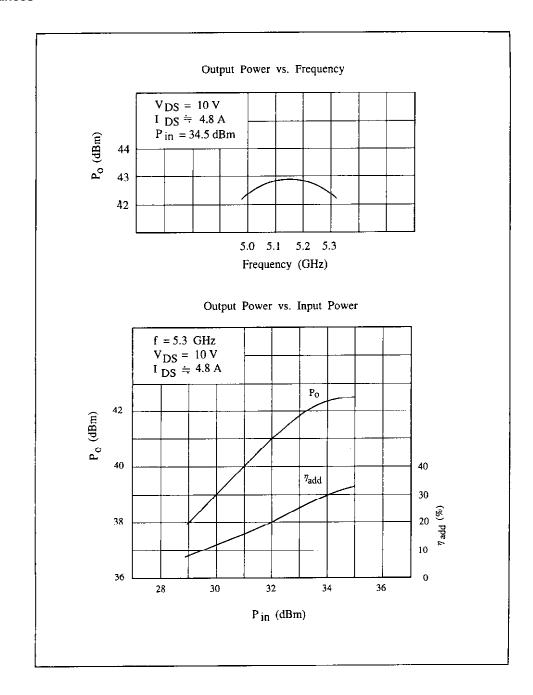
## **Handling Precautions for Packaged Type**

Soldering iron should be grounded and the operating time should not exceed 10 seconds at 260°C.

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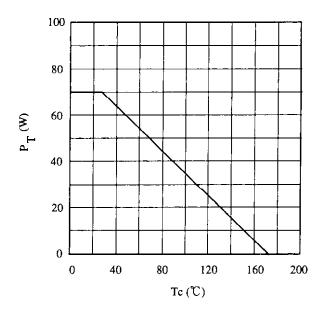
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### **RF Performances**



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# **Power Dissipation vs. Case Temperature**



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